

OPTIONS

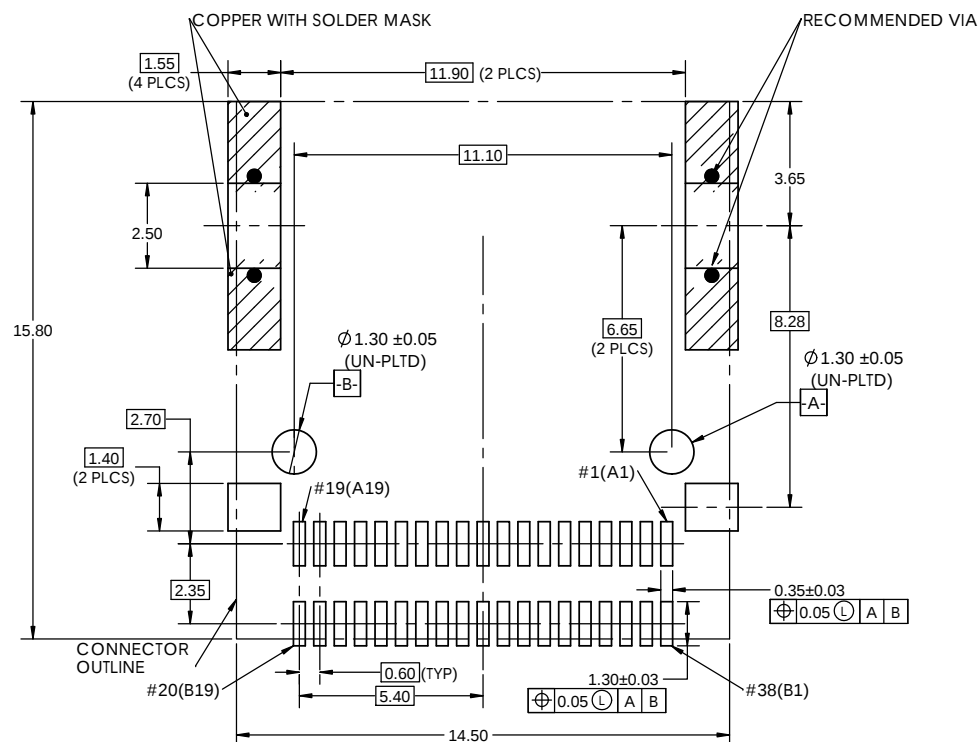
0T = STANDARD CONSTRUCTION WITH TAPE & REEL
PACKAGING

1T = NO RESONANCE DAMPING WITH TAPE & REEL
PACKAGING

CONTACT PLATING OPTION

2 = 30 MICROINCHES OF GOLD ON MATING END WITH 100 MICROINCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION. 50-75 MICROINCHES OF NICKEL UNDERPLATE ALL OVER

3 = 15 MICROINCHES OF GOLD ON MATING END WITH 100 MICROINCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION. 50-75 MICROINCHES OF NICKEL UNDERPLATE ALL OVER



NOTES:

1) MATERIAL:

HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0
CONTACTS: HIGH PERFORMANCE COPPER ALLOY
LATCH: PHOSPHOR BRONZE
RESONANCE DAMPENING FEATURE: SEMI-CONDUCTIVE POLYMER

2)RoHS COMPLIANT



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UNLESS SPECIFIED OTHERWISE		DRAWN		J.SI		DEC12/14		Amphenol High Speed Interconnects A Division of Amphenol Corp. www.amphenolcanada.com			
PRIMARY UNITS MILLIMETERS		CHECKED		M. E. APP'D				ULTRAPORT SLIMSAS™ 4X24 R/A RECEPTACLE WITH SMT LATCH			
SECONDARY				Q. A. APP'D							
REFERENCE IN PARENTHESES				DWG. APP'D							
GENERAL TOLERANCES		±0.35		ECN TBD				P-U10-C038-X1XX REV F			
1 DECIMAL PLACE		±0.25		REF.		DWG. NO.					
2 DECIMAL PLACES		±0.15									
3 DECIMAL PLACES		±0.1									
ANGULAR DEGREES		±2°		THIRD ANGLE PROJECTION 		DO NOT SCALE DRAWING 		CODE ID NO. 03554		DWG SIZE: C	
								SCALE: 5:1		SHEET 1 OF 1	